

### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	I <sub>PP_I/O</sub>	±6	Α	I/O to V <sub>SS</sub> , 8/20µs
Peak Pulse Power, per IEC 61000-4-5	P <sub>PP_I/O</sub>	55	W	I/O to V <sub>SS</sub> , 8/20µs
Operating Voltage (DC)	V <sub>DC</sub>	5.5	V	I/O to V <sub>SS</sub>
ESD Protection – Contact Discharge, per IEC 61000-4-2	V <sub>ESD_I/O</sub>	±16	kV	I/O to V <sub>SS</sub>
ESD Protection – Air Discharge, per IEC 61000-4-2	V <sub>ESD_I/O</sub>	+27/-19	kV	I/O to V <sub>SS</sub>
Operating Temperature	T <sub>OP</sub>	-55 to +85	°C	_
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C	_

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	$P_{D}$	300	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{ heta JA}$	417	°C/W

## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

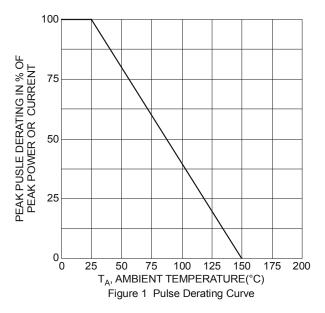
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	VRWM	_	_	5.0	V	V <sub>CC</sub> to V <sub>SS</sub>
Reverse Current (Note 6)	I <sub>R(</sub> V <sub>cc to</sub> V <sub>ss)</sub>	_	_	1.0	μA	V <sub>R</sub> = V <sub>RWM</sub> = 5V, V <sub>CC</sub> to V <sub>SS</sub>
Reverse Current (Note 6)	I <sub>R(IO to</sub> V <sub>ss)</sub>	-	_	0.5	μA	$V_R = V_{RWM} = 5V$ , any I/O to $V_{SS}$
Reverse Breakdown Voltage	V <sub>BR</sub>	6.2	_	-	V	I <sub>R</sub> = 1mA, V <sub>CC</sub> to V <sub>SS</sub>
Forward Clamping Voltage	$V_{F}$	-1.0	-0.8	-	V	I <sub>F</sub> = -15mA, V <sub>CC</sub> to V <sub>SS</sub>
Reverse Clamping Voltage(Note 7)	$V_{C_{-}}V_{cc}$	-	6.3	-	V	I <sub>PP</sub> = 9A, V <sub>CC</sub> to V <sub>SS</sub> , 8/20 μs
	V <sub>C_I/O</sub>	-	7.7	9	V	I <sub>PP</sub> = 6A, I/O to V <sub>SS</sub> , 8/20 μs
ESD Clamping Voltage	$V_{\text{ESD}}V_{\text{cc}}$	-	6.8	-	V	TLP, 10A, tp = 100 ns, $V_{CC}$ to $V_{SS}$ , per Fig. 8
	V <sub>ESD_I/O</sub>	-	9	-	V	TLP, 10A, tp = 100 ns, I/O to $V_{SS}$ , per Fig. 8
Dynamic Resistance	R <sub>DIF</sub> _V <sub>cc</sub>	-	0.1	-	Ω	TLP, 10A, tp = 100 ns, $V_{CC}$ to $V_{SS}$
	R <sub>DIF_I/O</sub>	-	0.25	-	Ω	TLP, 10A, tp = 100 ns, I/O to $V_{SS}$
Channel Input Capacitance	C <sub>I/O to</sub> V <sub>SS</sub>	_	0.65	0.8	pF	V <sub>R</sub> = 2.5V, V <sub>CC</sub> = 5V, f = 1MHz
Variation of Channel Input Capacitance	$\Delta C_{I/O}$	-	0.02	-	pF	V <sub>CC</sub> = 5V, V <sub>SS</sub> = 0V, I/O = 2.5V, f = 1MHz, T = +25°C , I/O_x to V <sub>SS</sub> - I/O_y to V <sub>SS</sub>

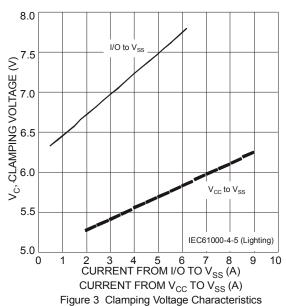
Notes:

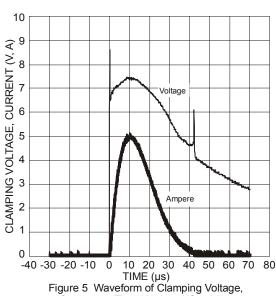
- 5. Device mounted on Polymide PCB pad layout (2oz copper) as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website
- at http://www.diodes.com.

  6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an  $8x20\mu s$  peak pulse current ( $I_{pp}$ ) waveform.









Current vs. Time (8/20µs, I/O to V<sub>SS</sub>)

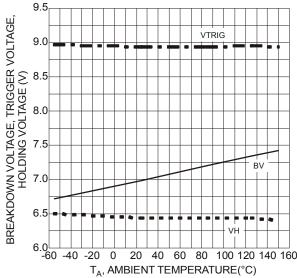


Figure 2 Breakdown Voltage, Trigger Voltage, Holding Voltage vs. Ambient Temperature

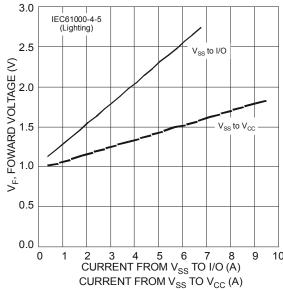
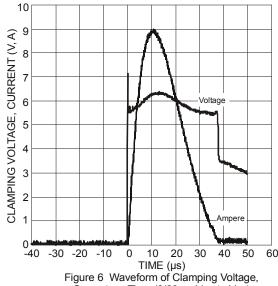
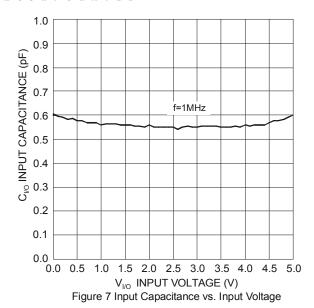


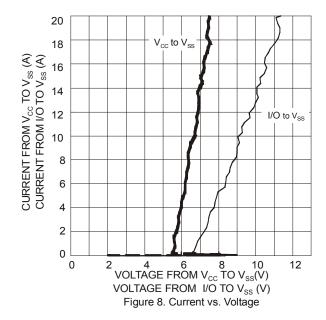
Figure 4 Forward Voltage Characteristics



Current vs. Time (8/20µs, V<sub>CC</sub> to V<sub>SS</sub>)

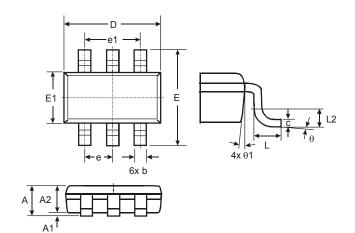






# **Package Outline Dimensions**

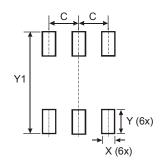
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TSOT26					
Dim	Min	Max	Тур		
Α	-	1.00	-		
A1	0.01	0.10	-		
A2	0.84	0.90	_		
D	_	_	2.90		
Е	_	_	2.80		
E1	_	_	1.60		
b	0.30	0.45	_		
С	0.12	0.20	_		
е	_	_	0.95		
e1	_	-	1.90		
L	0.30	0.50			
L2	_	-	0.25		
θ	0°	8°	4°		
θ1	4°	12°	-		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.950
X	0.700
Y	1.000
Y1	3.199



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